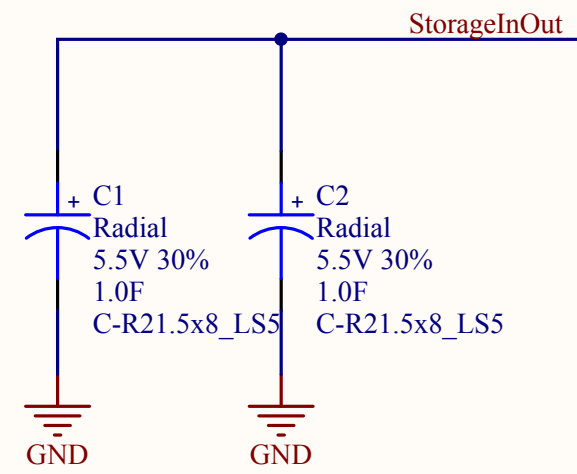
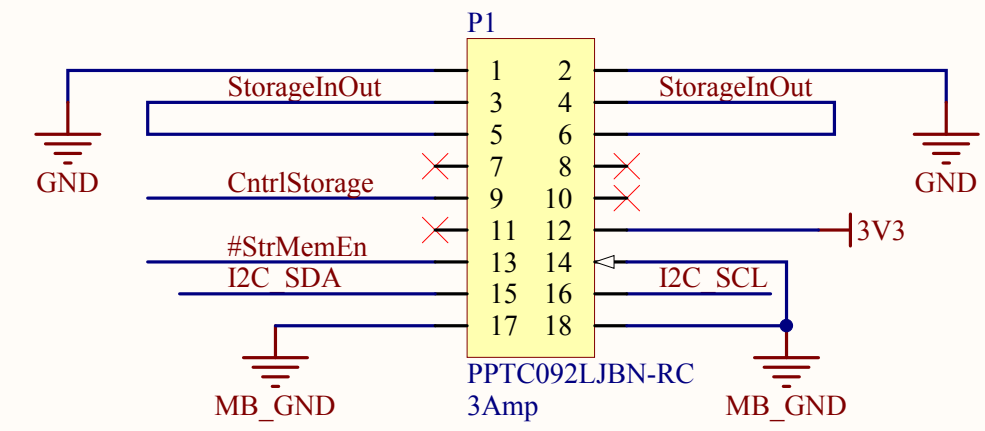


Storage

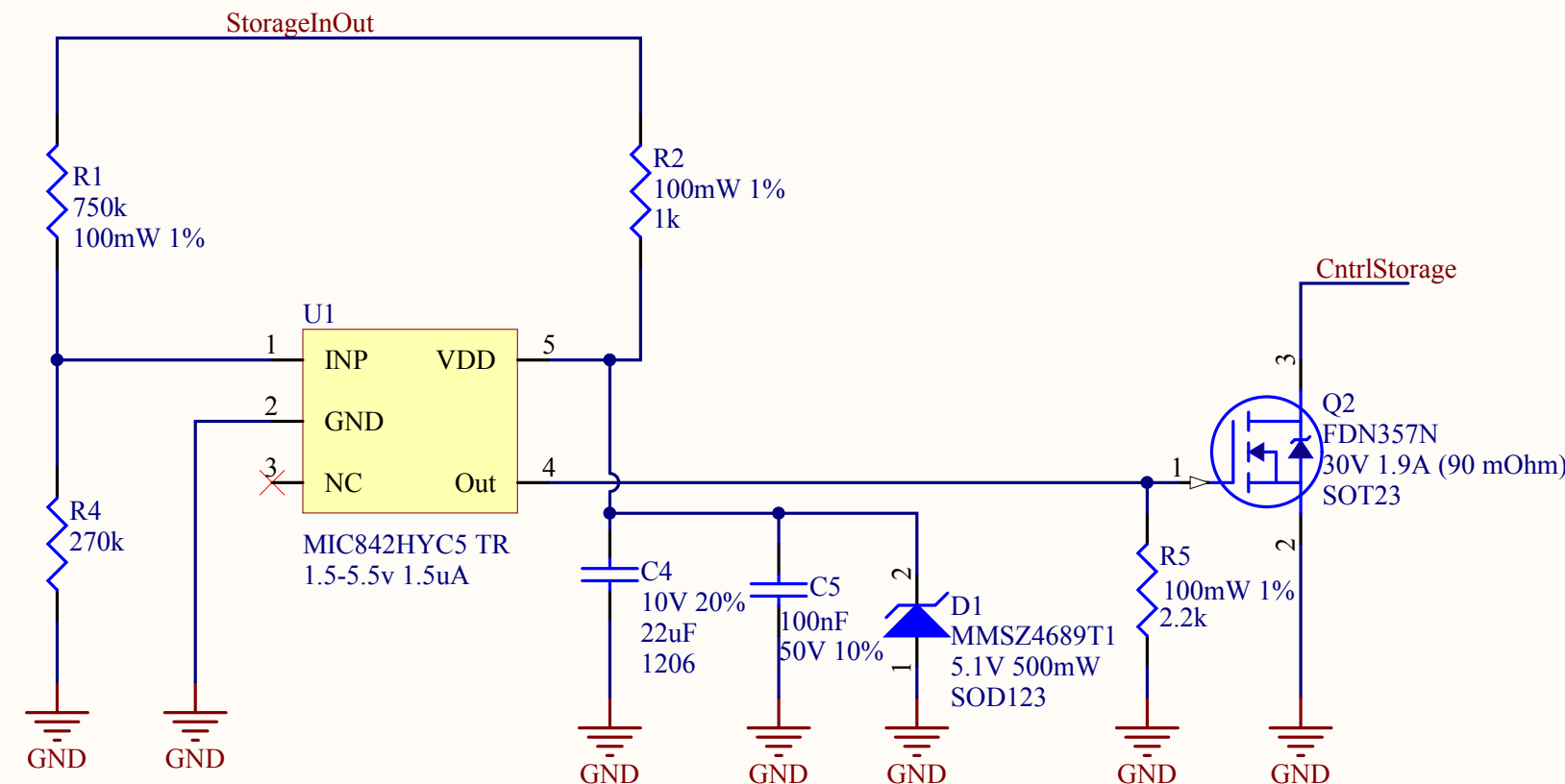


Connector

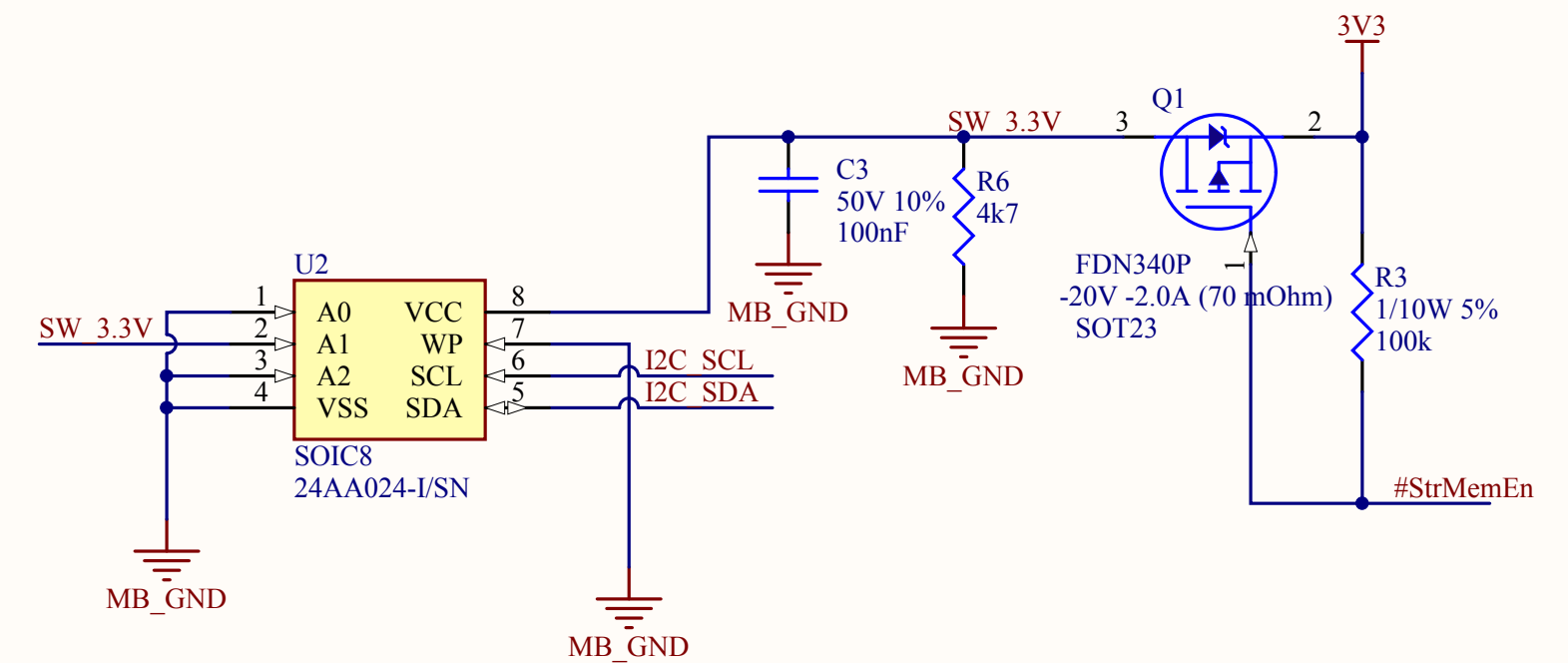


Vin = 5.5V (max)
 Vout = 4.68V (max)
 Iout = 200mA (typ)

Protection Circuit



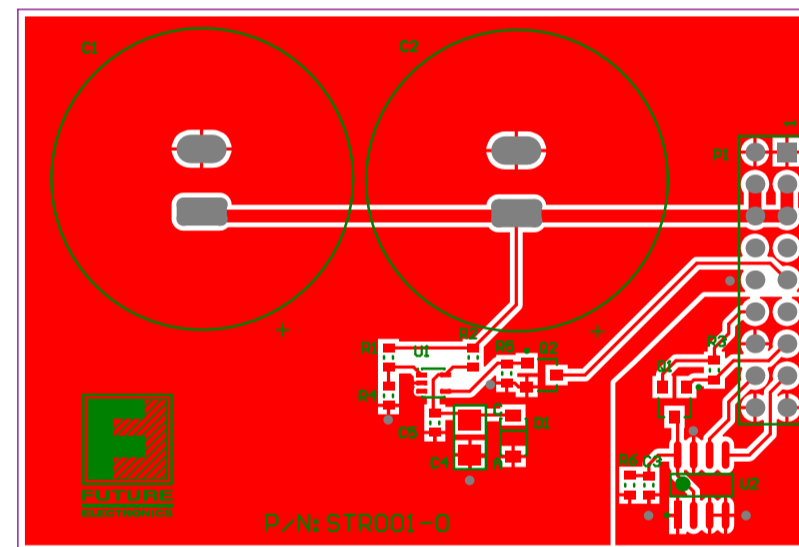
Block Memory



0603 footprints not shown

	Future Electronics - Advanced Engineering Group 237 Hymus Blvd. Pointe-Claire, Quebec, Canada H9R 5C7		
	Project Name STR_001_00.PrjPCB		
	Designed by N.Gautam		Title Energy Storage Board - Super Cap
	Drawn by N.Gautam		
Checked by H. Letourneau		Size B	Dwg No. FEN-2858-STR001-SCH-R0.0
Approved by H. Letourneau		Date 2012-02-15	
		Sheet 1 of 1	

REVISION			
REV.	DATE	DESCRIPTION	Done by



NOTES: < UNLESS OTHERWISE SPECIFIED >

- BOARD SPECS - BOARD SHALL BE MANUFACTURED TO MEET ALL SPECS DEFINED UNDER IPC-A-600.
- BASE MATERIAL - FR4 62mil±, COPPER 1/1 OZ./SQ.FT.
- PLATING - COPPER 1.0 OZ./SQ.FT.
- FINISH - LEAD FREE HASL
- GERBER FILES - SUPPLIED GERBER FILES MUST NOT BE MODIFIED BY MANUFACTURER WITHOUT PRIOR PERMISSION FROM THE CLIENT.
- DRILLING - ALL HOLES TO BE DRILLED CONCENTRIC TO THEIR CIRCULAR BASE TO WITHIN .01 RADIUS.
- REGISTRATION - REGISTRATION OF PATTERNS TO BE WITHIN .01 LOCATION OF PATTERN ON BOARD TO
- TOOLING HOLES - NO HOLES SHALL BE PERMITTED WITHIN THE BOARD AREA, EXCEPT THOSE INDICATED IN THE DRILL LEGEND.
- PLATED HOLES - HOLES TO BE PLATED-THROUGH TO A FINISHED DIAMETER AS SHOWN IN DRILL LEGEND, MINIMUM THICKNESS .0014 UNLESS OTHERWISE SPECIFIED.
- SOLDER MASK - APPLY GREEN SOLDER MASK AS PER SPECIFIED IPC-SM-840 TO BOTH SIDES OF PCB OVER BARE COPPER
- SILKSCREEN - APPLY ON COMPONENT TOPSIDE OF PCB IN WHITE EPOXY BASED INK.

- CONFIDENTIAL -
 THIS DRAWING CONTAINS PROPRIETARY INFORMATION WHICH MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE WHATSOEVER OR USED FOR MANUFACTURING PURPOSES WITHOUT PRIOR WRITTEN PERMISSION FROM THE FUTURE ELECTRONICS CORPORATION.

	FUTURE ELECTRONICS Future Electronics - Advanced Engineering Group 237 Hymus Blvd Pointe-Claire, Quebec, Canada H9R 5C7
	Project # Energy Harvesting Platform Title: Storage Solution Board (Super Cap)
Designed by: N. Gautam Drawn by: N. Gautam Checked by: N. Gautam Approved by: H. Letourneau	Size: B DWG NO: FEN-2858-STR001-PCB-R0 REV: 0 Date: Aug 23 2011 Sheet 1 of 1

REVISION			
REV.	DATE	DESCRIPTION	Done by

A

A

B

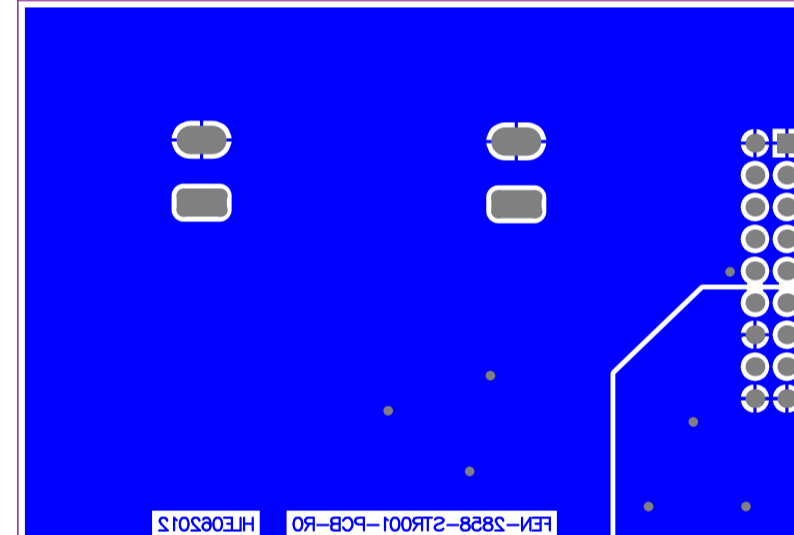
B

C

C

D

D



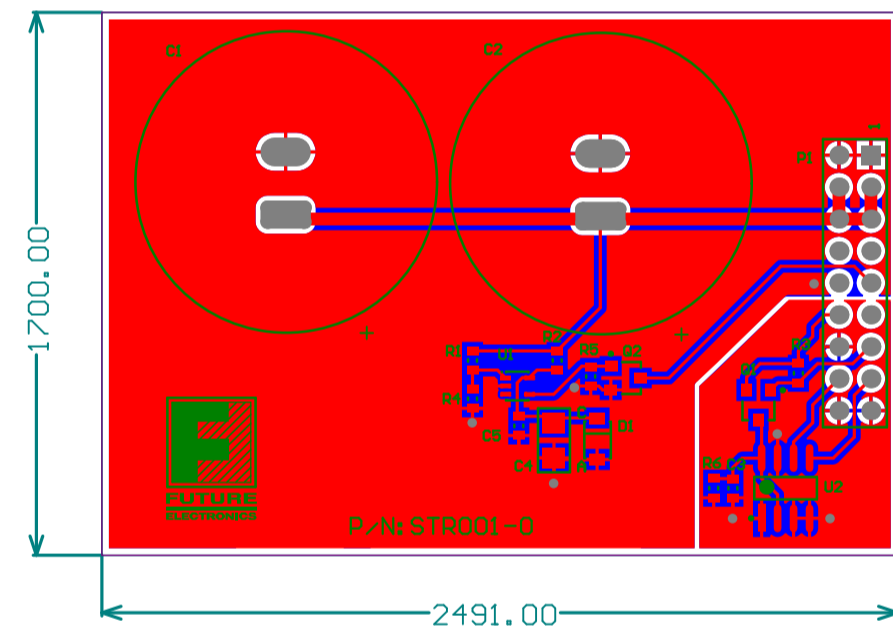
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	Drawn by: N. Gautam	Project # Energy Harvesting Platform	
	Checked by: N. Gautam	Title: Storage Solution Board (Super Cap)	
	Approved by: H. Letourneau	Size: B DWG NO: FEN-2858-STR001-PCB-R0	REV: 0
	Date: Aug 23 2011	Sheet 1 of 1	

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	FUTURE ELECTRONICS Future Electronics - Advanced Engineering Group 237 Hymus Blvd Pointe-Claire, Quebec, Canada H9R 5C7
	Designed by: N. Gautam Drawn by: N. Gautam Checked by: N. Gautam Approved by: H. Letourneau
	Project # Energy Harvesting Platform Title: Storage Solution Board (Super Cap) Size: B DWG NO: FEN-2858-STRO01-PCB-R0 REV: 0 Date: Aug 23 2011 Sheet 1 of 1

